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(71) Applicant *(for all designated States except US)*: **LAM RESEARCH CORPORATION** [US/US]; 4650 Cushing Parkway, Fremont, CA 94538 (US).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **REN, Daxing** [CN/US]; 6420 Stoneridge Mall Road, Apartment M203, Pleasanton, CA 94588 (US). **HUBACEK, Jerome, S.** [US/US]; 644 Hobart Court, Fremont, CA 94539 (US). **WEBB, Nicholas, E.** [US/US]; 1812 Kennedy Drive, Milpitas, CA 95035 (US).

(74) Agent: **PETERSON, James, W.**; Burns, Doane, Swecker & Mathis, LLP, P.O. Box 1404, Alexandria, VA 22313-1404 (US).

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(54) Title: SILICON PARTS FOR PLASMA REACTION CHAMBERS

(57) Abstract: Silicon parts of a semiconductor processing apparatus containing low levels of metal impurities that are highly mobile in silicon are provided. The silicon parts include, for example, rings, electrodes and electrode assemblies. The silicon parts can reduce metal contamination of wafers processed in plasma atmospheres.